ON Semiconductor®

Product Bulletin

Document #:PB22863X
Issue Date:11 Oct 2019

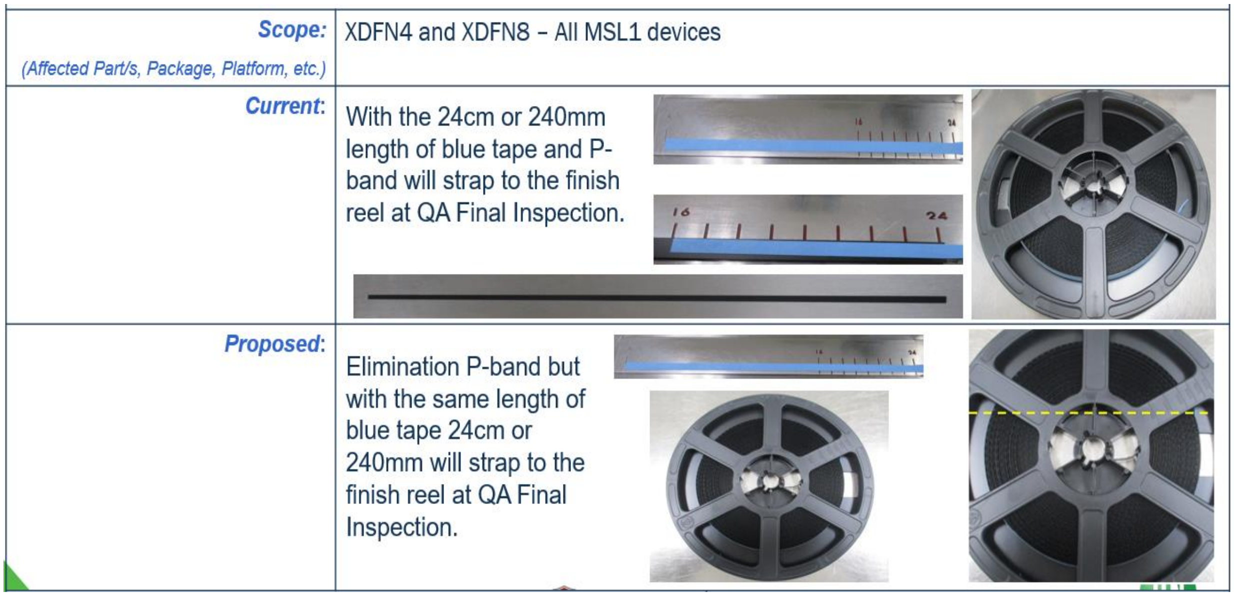
Title of Change:	ELIMINATION OF PBAND MATERIAL FOR XDFN4 AND XDFN8 PACKAGES
Effective date:	11 Oct 2019
Contact information:	Contact your local ON Semiconductor Sales Office or Ryan.Baun@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Assembly Change
Change Sub-Category(s):	Shipping/Packaging/Marking, Protective Band

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
ON Semiconductor Tarlac, Philippines	None

Description and Purpose:

This is to announce the elimination of the Protective Band for MSL 1 parts in XDFN4 and XDFN8 packages at Tarlac site. P-Band is a protective band which protects the units/carrier tape from damages and prevent reel from crushing when using dry pack /vacuum seal. However, Tarlac site does not have dry packing and vacuum sealing thus the use of Protective Band is not required.



Scope: *(Affected Part/s, Package, Platform, etc.)*	XDFN4 and XDFN8 – All MSL1 devices
Current:	With the 24cm or 240mm length of blue tape and P-band will strap to the finish reel at QA Final Inspection.
Proposed:	Elimination P-band but with the same length of blue tape 24cm or 240mm will strap to the finish reel at QA Final Inspection.

List of Affected Standard Parts:

***Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

NCP186AMX120TAG	NCP717CMX285TBG	NCP707AMX285TCG
NCP161AMX180TBG	NCP170AMX120TCG	NCP160AMX180TBG